

MRS Invites Nominations for the Von Hippel Award, MRS Medal, and Turnbull Lectureship

The Materials Research Society is seeking nominations for the Von Hippel Award, the MRS Medal, and the Turnbull Lectureship. The deadline for nominations is **June 1, 1996**. These awards will be presented at the 1996 MRS Fall Meeting, December 2–6, in Boston.

The MRS Awards Program recognizes outstanding contributors to the progress of materials research. Nomination forms and details about eligibility and nomination criteria are available from Anne Wagner, Materials Research Society, 9800 McKnight Road, Pittsburgh, PA 15237-6006; phone 412-367-3004 ext. 102; fax 412-367-4373. Further information about each award can also be obtained from MRS homepage on the World Wide Web: <http://www.mrs.org>.

Von Hippel Award Acknowledges Outstanding Interdisciplinary Work in Materials Research

The Von Hippel Award, first presented to Arthur R. von Hippel whose interdisciplinary and pioneering research typified

the spirit of the award, is the Materials Research Society's highest honor. The recipient is recognized for brilliance and originality combined with vision that transcends the boundaries of conventional scientific disciplines. The Award includes a \$7,500 cash prize, honorary membership to MRS, and a unique trophy—a mounted ruby laser crystal symbolizing the multifaceted nature of materials research.

Selection of the recipient is determined by a vote of the MRS Council. The recipient will be invited to speak at the Awards Ceremony.

Turnbull Lectureship Honors Career of an Outstanding Researcher and Communicator

The David Turnbull Lectureship recognizes the career of a scientist who has made outstanding contributions to understanding materials phenomena and properties through research, writing, and lecturing, as exemplified by the life work of David Turnbull. While honoring the accomplishments of the recipient, the Turnbull

Lectureship is intended to support and enrich the materials research community.

The recipient will give a technical lecture of broad appeal at a designated session of the 1996 MRS Fall Meeting. The Turnbull Lecturer will receive a \$3,000 honorarium and a citation plaque, along with travel expenses paid to enable the recipient to address MRS Sections and University Chapters, and/or participate in the production of a video version of the lecture.

MRS Medals Recognize Recent Discoveries or Advancements in Materials Science

The MRS Medals offer public and professional recognition of exceptional recent achievements in materials research. Two medals will be awarded for specific outstanding recent discoveries or advancements which are expected to have major impacts on the progress of any materials-related field.

Each award consists of a \$2,000 cash prize, an engraved and mounted medal, and a citation certificate. MRS

Previous Recipients of the Von Hippel Award

Arthur R. von Hippel
Massachusetts Institute of Technology

William O. Baker
AT&T Bell Laboratories

David Turnbull
Harvard University

W. Conyers Herring
Stanford University

James W. Mayer
Cornell University

Clarence M. Zener
Carnegie-Mellon University

Sir Peter B. Hirsch
University of Oxford

Walter L. Brown
AT&T Bell Laboratories

John W. Cahn
National Bureau of Standards

Minko Balkanski
Universite Pierre et Marie Curie

Sir Charles Frank
University of Bristol

Jacques Friedel
Universite de Paris-Sud

John B. Goodenough
University of Texas—Austin

Robert W. Balluffi
Massachusetts Institute of Technology

Theodore H. Geballe
Stanford University

Michael F. Ashby
Cambridge University

Frederick Seitz
The Rockefeller University

Alfred Y. Cho
AT&T Bell Laboratories

William W. Mullins
Carnegie-Mellon University

Previous Recipients of the MRS Medal

Arthur J. Freeman
Northwestern University

Duward F. Shriver
Northwestern University

Bernard S. Meyerson
IBM T.J. Watson Research Center

Shigeyuki Sōmiya
Nishi Tokyo University

L. Eric Cross
The Pennsylvania State University

Stephen J. Pennycook
Oak Ridge National Laboratory

Wolfgang Krätschmer
Max-Planck Institute für Kernphysik

Donald R. Huffman
University of Arizona

Max G. Lagally
University of Wisconsin—Madison

Kenneth S. Suslick
University of Illinois at Urbana-Champaign

Federico Capasso
AT&T Bell Laboratories

Rudolf M. Tromp
IBM T.J. Watson Research Center

Previous Recipients of the Turnbull Lectureship

Thomas R. Anthony
General Electric Company

Morris Cohen
Massachusetts Institute of Technology

Arthur S. Nowick
Columbia University

Didier R. de Fontaine
University of California—Berkeley

(As of January 1996)

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